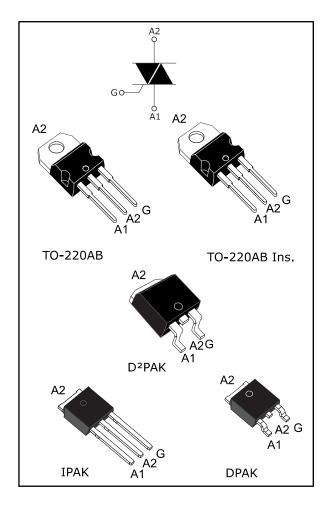


BTA08, BTB08, T810, T835, T850

Snubberless™, logic level and standard 8 A Triacs

Datasheet - production data



Features

- On-state rms current, I_{T(RMS)} 8 A
- Repetitive peak off-state voltage, V_{DRM} / V_{RRM} 600 V to 800 V
- Triggering gate current, I_{GT (Q1)} 5 to 50 mA

Description

Available either in through-hole and surfacemount packages, these devices are suitable for general purpose AC switching. They can be used as an ON/OFF function in applications such as static relays, heating regulation, induction motor starting circuits or for phase control operation in light dimmers and motor speed controllers, etc.

The Snubberless versions (BTA, BTB08_xxxxW and T8 series) are specially recommended for use on inductive loads, thanks to their high commutation performance.

Logic level versions are designed to interface directly with low power drivers such as Microcontrollers.

By using an internal ceramic pad, the BTA series provide voltage insulated tab (rated at 2500 V_{RMS}) in compliance with UL standards (file ref.: E81734).

1 Characteristics

Table 1: Absolute maximum ratings (T_j = 25 °C unless otherwise stated)

Symbol	Paran	neter		Value	Unit
I _{T(RMS)}	RMS on-state current (full sine wave)	IPAK, DPAK, TO-220AB, D²PAK	T _c = 110 °C	8	А
		TO-220ABIns.	T _c = 100 °C		
	Non repetitive surge peak	f = 50 Hz	t = 20 ms	80	
Ітѕм	on-state current (full cycle, T_j initial = 25 °C)	f = 60 Hz	t _p = 16.7 ms	84	Α
l ² t	I ² t value for fusing		t _p = 10 ms	36	A ² s
dl/dt	Critical rate of rise of on-state current I _G = 2 x I _{GT} , tr ≤ 100 ns	f = 120 Hz	T _j = 125 °C	50	A/µs
l _{GM}	Peak gate current	t _p = 20 μs	T _j = 125 °C	4	Α
P _{G(AV)}	Average gate power dissipation	1	W		
T _{stg}	Storage junction temperature range	-40 to +150	°C		
Tj	Operating junction temperature ran	ige		-40 to +125	°C

Table 2: Electrical characteristics (T_j = 25 °C, unless otherwise specified) Snubberless and logic level (3 quadrants)

Cumbal	Parameter	Quadrant			T8			BTA08	/BTB0	8	l lmit
Symbol	Oymbol I arameter	Quadrant		10	35	50	TW	sw	CW	BW	Unit
I _{GТ} ⁽¹⁾	V _D = 12 V,	1 - 11 - 111	Max.	10	35	50	5	10	35	50	mA
V_{GT}	$R_L = 30 \Omega$	1 - 11 - 111	Max.				1.2				V
V _{GD}	$\begin{split} V_D &= V_{DRM}, \\ R_L &= 3.3 \text{ k}\Omega, \\ T_j &= 125 \text{ °C} \end{split}$	1 - 11 - 111	Min.				0.2				V
IH ⁽²⁾	I⊤ = 100 mA		Max.	15	35	50	10	15	35	50	mA
1.	l- 10 x l	I - III	Max.	25	50	70	10	25	50	70	m 1
IL	l _G = 1.2 х l _{GT}	=	Max.	30	60	80	15	30	60	80	mA
dV/dt	$V_D = 67\% V_{DR}$ gate open, $T_j =$		Max.	40	400	1000	20	40	400	1000	V/µs
	$(dV/dt)c = 0.1 V/\mu s,$ $T_j = 125 °C$		Min.	5.4			3.5	5.4			
(dl/dt)c	(dV/dt)c = 10 V $T_j = 125 °C$	//μs,	Min.	2.8			1.5	2.98			A/ms
	Without snubb $T_j = 125$ °C	er,	Min.		4.5	7			4.5	7	

Notes:

4

 $^{{}^{(1)}\}mbox{Minimum IgT}$ is guaranteed at 5 % of IgT max.

⁽²⁾For both polarities of A2 referenced to A1

Table 3: Standard (4 quadrants)

Cumbal	Parameter	Quadrant		BTA08/	BTB08	Unit	
Symbol	Parameter	Quadrant		С	В	Oill	
I _{GT} ⁽¹⁾		1 - 11 - 111	Max.	25	50	mA	
IGI V	$V_D = 12 \text{ V}, R_L = 33 \Omega$	IV	IVIAX.	50	100	IIIA	
V _{GT}		All	Max.	1	1.3		
V _{GD}	$V_D = V_{DRM}, R_L = 33 \Omega, T_j = 125 ^{\circ}C$	All	Min.	0.2		V	
IH ⁽²⁾	I _T = 500 mA		Max.	25	50	mA	
ı.	lg = 1.2 lg	I - III - IV	Max.	40	50	m A	
Iι	IG = 1.2 IGT	II	IVIAX.	80	100	mA	
dV/dt ⁽²⁾	V _D = 67 % V _{DRM} gate open, T _j = 125 °C		Min.	200	400		
(dl/dt)c ⁽²⁾	(dl/dt)c = 5.3 A/ms, T _j = 125 °C		Min.	5	10	V/µA	

Table 4: Static electrical characteristics

Symbol	Test conditions		Value	Unit	
V _{TM} ⁽¹⁾	$I_{TM} = 11 \text{ A, } t_p = 380 \mu\text{s}$	T _j = 25 °C	Max.	1.55	V
V _{TO} ⁽¹⁾	threshold on-state voltage	T _j = 125 °C	Max.	0.85	V
R _D ⁽¹⁾	Dynamic resistance	T _j = 125 °C	Max.	50	mΩ
I _{DRM} I _{RRM}	N N	T _j = 25 °C	Max.	5	μΑ
	V _{DRM} = V _{RRM}	T _j = 125 °C	Max.	1	V V mΩ

Notes:

Table 5: Thermal resistance

Symbol		Parameter					
R _{th(j-c)} Max. junction to case thermal resistance (AC)		IPAK / D2PAK / DPAK / TO-220AB	1.6	°C/W			
			TO-220AB Insulated	2.5	-C/VV		
	Junction to	$S^{(1)} = 1 \text{ cm}^2$	D²PAK	45			
D	ambient	S = 1 cm ²	DPAK	70	0000		
R _{th(j-a)}			TO-220AB / TO-220AB Insulated		°C/W		
	Junction to ambien	τ	IPAK	100			

Notes:

 $^{(1)}$ S = Copper surface under tab



 $^{^{(1)}}$ Minimum I_{GT} is guaranteed at 5 % of I_{GT} max.

⁽²⁾ For both polarities of A2 referenced to A1

⁽¹⁾For both polarities of A2 referenced to A1

1.1 Characteristics (curves)

Figure 1: Maximum power dissipation versus on-state RMS current (full cycle)

P(W)

P(W)

In the state of the

Figure 2: RMS on-state current versus temperature (full cycle) I_{T(RMS)}(A) 10 9 BTB/T8 8 7 вта 6 5 3 2 0 0 25 50 75 100 125

Figure 3: RMS on-state current versus ambient temperature (full cycle) $I_{T(RMS)}(A)$ 3.5 D²PAK Printed circuit board FR4, copper thickness: 35 µm $(S = 1 cm^2)$ 3.0 2.5 2.0 1.5 - DPAK _(S = 0.5 cm² 1.0 0.5 T_C(°C) 0.0 25 125

Figure 4: Relative variation of thermal impedance versus pulse duration

K = [Zth/Rth]

1E+0

DPAK/IPAK
Zth(j-a)

1E-2

1E-3

1E-3

1E-3

1E-1

1E-1

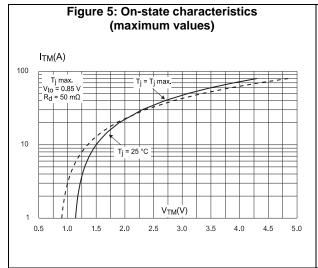
1E-2

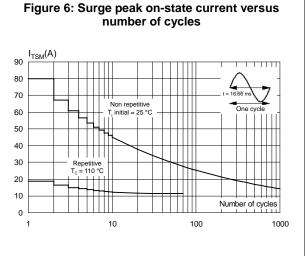
1E-1

1E-1

1E-2

1E-3

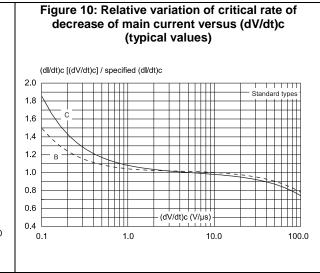


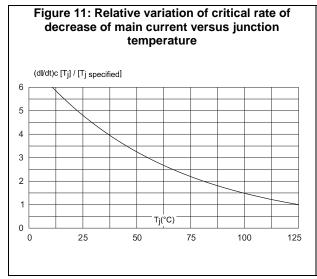


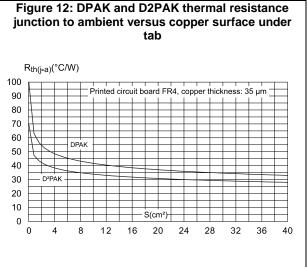
57

Figure 8: Relative variation of gate trigger current $I_{GT},I_{H},I_{L}[T_{j}] / I_{GT},I_{H},I_{L}[T_{j} = 25 °C]$ 2.5 2.0 1.5 1.0 IH and II 0.5 T_j (°C) 0.0 -40 -20 0 20 40 60 80 100 120 140

Figure 9: Relative variation of critical rate of decrease of main current versus (dV/dt)c (typical values) (dl/dt)c [(dV/dt)c / specified (dl/dt)c 22 Snubberless and logic level types 2.0 1.8 1.6 1.4 1.2 1.0 0.8 0.6 0.4 0.2 (dV/dt)c (V/µs) \blacksquare 0.0 1.0 100.0







2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: **www.st.com**. ECOPACK® is an ST trademark.

- Epoxy meets UL94, V0
- Lead-free package
- Recommended torque: 0.4 to 0.6 N·m

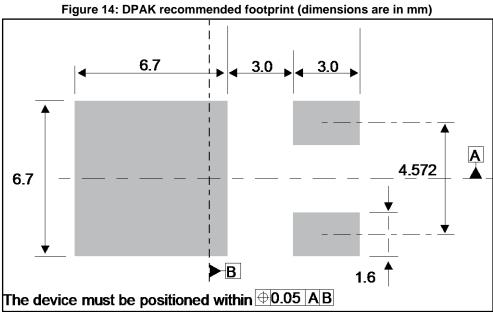
2.1 DPAK package information

Figure 13: DPAK package outline Ε b4 с2 \sim 5 I E1 e1 8

Table 6: DPAK package mechanical data

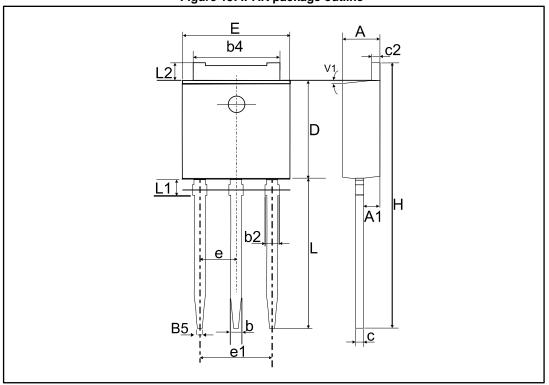
	Dimensions							
Ref.		Millimeters	 S		Inches ⁽¹⁾			
	Min.	Тур.	Max.	Min.	Тур.	Max.		
А	2.18		2.40	0.0858		0.0945		
A1	0.90		1.10	0.0354		0.0433		
A2	0.03		0.23	0.0012		0.0091		
b	0.64		0.90	0.0252		0.354		
b4	4.95		5.46	0.1949		0.2150		
С	0.46		0.61	0.0181		0.0240		
c2	0.46		0.60	0.0181		0.0236		
D	5.97		6.22	0.2350		0.2449		
D1	4.95		5.60	0.1949		0.2205		
Е	6.35		6.73	0.2500		0.2650		
E1	4.32		5.50	0.1701		0.2165		
е		2.29			0.0900			
e1	4.40		4.70	0.1732		0.1850		
Н	9.35		10.40	0.3681		0.4094		
L	1.00		1.78	0.0394		0.0701		
L2			1.27			0.0500		
L4	0.60		1.02	0.0236		0.0402		
V2	-8°		+8°	-8°		+8°		

⁽¹⁾Dimensions in inches are given for reference only



2.2 IPAK package information

Figure 15: IPAK package outline





This package drawing may slightly differ from the physical package. However, all the specified dimensions are guaranteed.

Table 7: IPAK package mechanical data

		Dimensions						
Ref.		Millimeters			Inches ⁽¹⁾			
	Min.	Тур.	Max.	Min.	Тур.	Max.		
А	2.20		2.40	0.0866		0.0945		
A1	0.90		1.10	0.0354		0.0433		
b	0.64		0.90	0.0252		0.0354		
b2			0.95			0.0374		
b4	5.20		5.43	0.2047		0.2138		
B5		0.30			0.0118			
С	0.45		0.60	0.0177		0.0236		
c2	0.46		0.60	0.0181		0.0236		
D	6.00		6.20	0.2362		0.2441		
Е	6.40		6.65	0.2520		0.2618		
е		2.28			0.0898			
e1	4.40		4.60	0.1732		0.1811		
Н		16.10			0.6339			
L	9.00		9.60	0.3545		0.3780		
L1	0.80		1.20	0.0315		0.0472		
L2		0.80	1.25		0.0315	0.0492		
V1		10°			10°			

⁽¹⁾Inch dimensions are for reference only.

2.3 TO-220AB (NIns. and Ins.) package information

Figure 16: TO-220AB (NIns. & Ins.) package outline

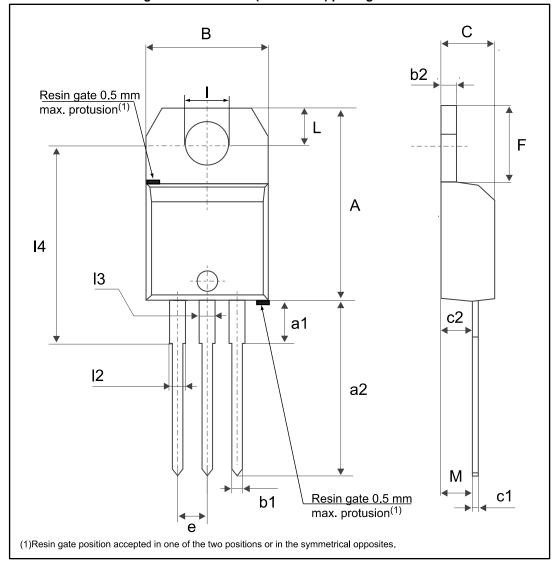


Table 8: TO-220AB (NIns. & Ins.) package mechanical data

				mensions		
Ref.		Millimeters			Inches ⁽¹⁾	
	Min.	Тур.	Max.	Min.	Тур.	Max.
А	15.20		15.90	0.5984		0.6260
a1		3.75			0.1476	
a2	13.00		14.00	0.5118		0.5512
В	10.00		10.40	0.3937		0.4094
b1	0.61		0.88	0.0240		0.0346
b2	1.23		1.32	0.0484		0.0520
С	4.40		4.60	0.1732		0.1811
c1	0.49		0.70	0.0193		0.0276
c2	2.40		2.72	0.0945		0.1071
е	2.40		2.70	0.0945		0.1063
F	6.20		6.60	0.2441		0.2598
I	3.73		3.88	0.1469		0.1528
L	2.65		2.95	0.1043		0.1161
12	1.14		1.70	0.0449		0.0669
13	1.14		1.70	0.0449		0.0669
14	15.80	16.40	16.80	0.6220	0.6457	0.6614
М		2.6			0.1024	

⁽¹⁾Inch dimensions are for reference only.

2.4 D²PAK package information

Figure 17: D²PAK package outline

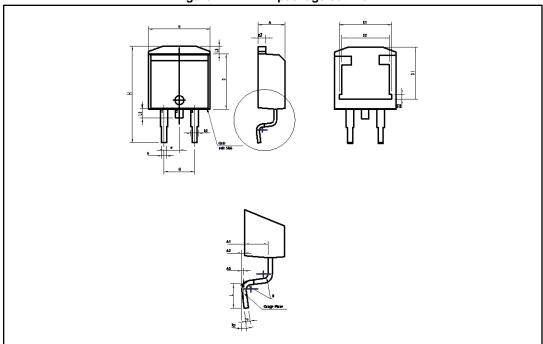
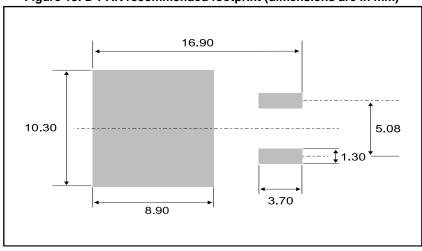


Table 9: D2PAK package mechanical data

	Table 9: D ² PAK package mechanical data							
			D	imensions				
Ref.		Millimeters			Inches ⁽¹⁾			
	Min.	Тур.	Max.	Min.	Тур.	Max.		
Α	4.30		4.60	0.1693		0.1811		
A1	2.49		2.69	0.0980		0.1059		
A2	0.03		0.23	0.0012		0.0091		
A3		0.25			0.0098			
В	0.70		0.93	0.0276		0.0366		
B2	1.25		1.7	0.0492		0.0669		
С	0.45		0.60	0.0177		0.0236		
C2	1.21		1.36	0.0476		0.0535		
D	8.95		9.35	0.3524		0.3681		
D1	7.50		8.00	0.2953		0.3150		
D2	1.30		1.70	0.0512		0.0669		
е	2.54			0.1				
Е	10.00		10.28	0.3937		0.4047		
E1	8.30		8.70	0.3268		0.3425		
E2	6.85		7.25	0.2697		0.2854		
G	4.88		5.28	0.1921		0.2079		
Н	15		15.85	0.5906		0.6240		
L	1.78		2.28	0.0701		0.0898		
L2	1.27		1.40	0.0500		0.0551		
L3	1.40		1.75	0.0551		0.0689		
R		0.40			0.0157			
V2	0°		8°	0°		8°		

Figure 18: D²PAK recommended footprint (dimensions are in mm)



⁽¹⁾Dimensions in inches are given for reference only

3 Ordering information

Figure 19: Ordering information scheme (BTA08 and BTB08 series)

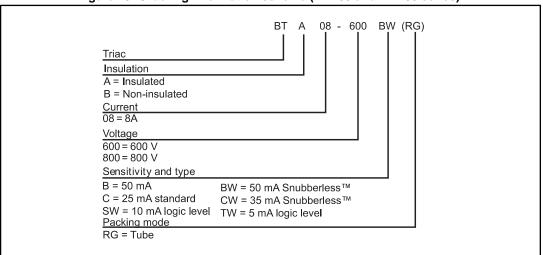


Figure 20: Ordering information scheme (T8 series)

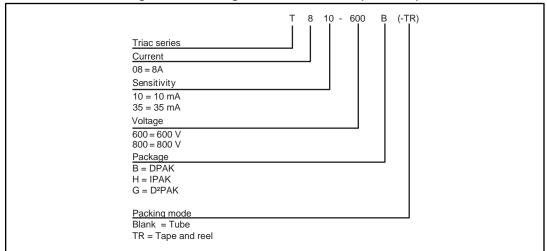


Table 10: Product selector

	Voltag	e (xxx)	ic 10.110ddot 30		
Part Number	600	800	Sensitivity	Туре	Package
T810-xxxB	Х	Х	10 mA	Logic Level	DPAK
T835-xxxH	Х		35 mA	Snubberless™	IPAK
T810-xxxG	Х		10 mA	Logic Level	D ² PAK
T835-xxxG	Х	Х	35 mA	Snubberless™	D ² PAK
T850-6G	Х		50 mA	Snubberless™	D ² PAK
BTA08-xxxS	Х		10 mA	Logic Level	TO-220AB Ins.
BTA08-xxxC	Х	Х	35 mA	Standard	TO-220AB Ins.
BTA08-xxxB	Х		50 mA	Standard	TO-220AB Ins.
BTA08-xxxTW	Х		5 mA	Logic Level	TO-220AB Ins.
BTA08-xxxSW	Х		10 mA	Logic Level	TO-220AB Ins.
BTA08-xxxCW	Х		35 mA	Snubberless™	TO-220AB Ins.
BTA08-xxxBW	Х	Х	50 mA	Snubberless™	TO-220AB Ins.
BTB08-xxxS	Х		10 mA	Logic Level	TO-220AB
BTB08-xxxC	Х		35 mA	Standard	TO-220AB
BTB08-xxxB	Х		50 mA	Standard	TO-220AB
BTB08-xxxTW	Х	Х	5 mA	Logic Level	TO-220AB
BTB08-xxxSW	Х		10 mA	Logic Level	TO-220AB
BTB08-xxxCW	Х	Х	35 mA	Snubberless™	TO-220AB
BTB08-xxxBW	Х		50 mA	Snubberless™	TO-220AB

Table 11: Ordering information

Order code	Marking	11: Ordering into	Weight	Base qty.	Delivery mode
		rackage	Weight	Dase quy.	Delivery mode
T810-600B	T8 1060				- .
T835-600B	T8 3560			75	Tube
T835-800B	T8 3580				
T810-600B-TR	T8 1060	DPAK	0.30		
T810-800B-TR	T8 1080			2500	Tape&Reel 13"
T835-600B-TR	T8 3560				
T835-800B-TR	T8 3580				
T835-600H	T8 3560	IPAK	0.40	75	Tube
T835-600G	T835-600G			50	Tube
T850-6G	T850-6G			- 50	Tube
T810-600G-TR	T810-600G	D2PAK	1.50		
T835-600G-TR	T835-600G			1000	Tape&Reel 13"
T850-6G-TR	T850-6G				
BTA08-600SRG	BTA08-600S				
BTA08-600BRG	BTA08-600B				
BTA08-600CRG	BTA08-600C				
BTA08-800CRG	BTA08-800C				
BTA08-600BWRG	BTA08-600BW	TO-220AB Ins.			
BTA08-600CWRG	BTA08-600CW				
BTA08-600SWRG	BTA08-600SW				
BTA08-600TWRG	BTA08-600TW				
BTA08-800BWRG	BTA08-800BW				
BTB08-600BRG	BTB08-600B		2.30	50	Tube
BTB08-600CRG	BTB08-600C				
BTB08-600SRG	BTB08-600S				
BTB08-600BWRG	BTB08-600BW				
BTB08-600CWRG	BTB08-600CW	TO-220AB			
BTB08-600SWRG	BTB08-600SW				
BTB08-600TWRG	BTB08-600TW				
BTB08-800CWRG	BTB08-800CW				
BTB08-800TWRG	BTB08-800TW				

4 Revision history

Table 12: Document revision history

Date	Revision	Changes
Apr-2002	5A	Last update.
13-Feb-2006	6	TO-220AB delivery mode changed from bulk to tube. ECOPACK statement added.
10-Mar-2010	7	Updated ECOPACK statement and Figure 26
02-Jun-2014	8	Updated DPAK and IPAK package information and reformatted to current standard.
07-Nov-2016	9	Updated Table 1 and reformatted to current standard.
06-Jan-2017	10	Updated Figure 20: "Ordering information scheme (T8 series)", Table 10: "Product selector" and Table 11: "Ordering information".
09-Feb-2017	11	Added T850 package information.
24-Apr-2017 12		Updated <i>Figure 6</i> . Minor text changes to improve readability.

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